INTEGRATED CIRCUITS



Product specification

1998 Nov 03

IC17 Data Handbook



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SA572

DESCRIPTION

The SA572 is a dual-channel, high-performance gain control circuit in which either channel may be used for dynamic range compression or expansion. Each channel has a full-wave rectifier to detect the average value of input signal, a linearized, temperature-compensated variable gain cell (Δ G) and a dynamic time constant buffer. The buffer permits independent control of dynamic attack and recovery time with minimum external components and improved low frequency gain control ripple distortion over previous compandors.

The SA572 is intended for noise reduction in high-performance audio systems. It can also be used in a wide range of communication systems and video recording applications.

FEATURES

- Independent control of attack and recovery time
- Improved low frequency gain control ripple
- Complementary gain compression and expansion with external op amp
- Wide dynamic range—greater than 110dB
- Temperature-compensated gain control
- Low distortion gain cell
- Low noise—6µV typical
- Wide supply voltage range—6V-22V
- System level adjustable with external components

PIN CONFIGURATION



Figure 1. Pin Configuration

APPLICATIONS

- Dynamic noise reduction system
- Voltage control amplifier
- Stereo expandor
- Automatic level control
- High-level limiter
- Low-level noise gate
- State variable filter

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
16-Pin Plastic Small Outline (SOL)	−40 to +85°C	SA572D	SOT162-1
16-Pin Plastic Dual In-Line Package (DIP)	−40 to +85°C	SA572N	SOT38-4

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	22	V _{DC}
T _A	Operating temperature range SA572	-40 to +85	°C
P _D	Power dissipation	500	mW

BLOCK DIAGRAM



Figure 2. Block Diagram

DC ELECTRICAL CHARACTERISTICS

Standard test conditions (unless otherwise noted) V_{CC} =15V, T_A =25°C; Expandor mode (see Test Circuit). Input signals at unity gain level (0dB) = 100mV_{RMS} at 1kHz; $V_1 = V_2$; $R_2 = 3.3k\Omega$; $R_3 = 17.3k\Omega$.

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SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Мах	UNIT	
V _{CC}	Supply voltage		6		22	V _{DC}	
I _{CC}	Supply current	No signal			6.3	mA	
V _R	Internal voltage reference		2.3	2.5	2.7	V _{DC}	
THD THD THD	Total harmonic distortion (untrimmed) Total harmonic distortion (trimmed) Total harmonic distortion (trimmed)	1kHz C _A =1.0μF 1kHz C _R =10μF 100Hz		0.2 0.05 0.25	1.0	% % %	
	No signal output noise	Input to V_1 and V_2 grounded (20–20kHz)		6	25	μV	
	DC level shift (untrimmed)	Input change from no signal to $100 \text{mV}_{\text{RMS}}$		±20	±50	mV	
	Unity gain level		-1.5	0	+1.5	dB	
	Large-signal distortion	V ₁ =V ₂ =400mV		0.7	3	%	
	Tracking error (measured relative to value at unity gain)= $[V_O - V_O$ (unity gain)]dB $-V_2$ dB	Rectifier input V ₂ =+6dB V ₁ =0dB V ₂ =-30dB V ₁ =0dB		±0.2 ±0.5	-2.5, +1.6	dB dB	
	Channel crosstalk	200mV _{RMS} into channel A, measured output on channel B	60			dB	
PSRR	Power supply rejection ratio	120Hz		70		dB	



TEST CIRCUIT

Figure 3. Test Circuit

AUDIO SIGNAL PROCESSING IC COMBINES VCA AND FAST ATTACK/SLOW RECOVERY LEVEL SENSOR

In high-performance audio gain control applications, it is desirable to independently control the attack and recovery time of the gain control signal. This is true, for example, in compandor applications for noise reduction. In high end systems the input signal is usually split into two or more frequency bands to optimize the dynamic behavior for each band. This reduces low frequency distortion due to control signal ripple, phase distortion, high frequency channel overload and noise modulation. Because of the expense in hardware, multiple band signal processing up to now was limited to professional audio applications.

With the introduction of the Signetics SA572 this high-performance noise reduction concept becomes feasible for consumer hi fi applications. The SA572 is a dual channel gain control IC. Each channel has a linearized, temperature-compensated gain cell and an improved level sensor. In conjunction with an external low noise op amp for current-to-voltage conversion, the VCA features low distortion, low noise and wide dynamic range.

The novel level sensor which provides gain control current for the VCA gives lower gain control ripple and independent control of fast attack, slow recovery dynamic response. An attack capacitor C_A with an internal 10k resistor R_A defines the attack time t_A . The recovery time t_R of a tone burst is defined by a recovery capacitor C_R and an internal 10k resistor R_R . Typical attack time of 4ms for the high-frequency spectrum and 40ms for the low frequency band can be obtained with $0.1\mu F$ and $1.0\mu F$ attack capacitors, respectively. Recovery time of 200ms can be obtained with a 4.7 μF recovery capacitor for a 100Hz signal, the third harmonic distortion is improved by more than 10dB over the simple RC ripple filter with a single $1.0\mu F$ attack and recovery capacitor, while the attack time remains the same.

The SA572 is assembled in a standard 16-pin dual in-line plastic package and in oversized SOL package. It operates over a wide supply range from 6V to 22V. Supply current is less than 6mA. The SA572 is designed for applications from -40° C to $+85^{\circ}$ C.

Programmable analog compandor

SA572 BASIC APPLICATIONS

Description

The SA572 consists of two linearized, temperature-compensated gain cells (Δ G), each with a full-wave rectifier and a buffer amplifier as shown in the block diagram. The two channels share a 2.5V common bias reference derived from the power supply but otherwise operate independently. Because of inherent low distortion, low noise and the capability to linearize large signals, a wide dynamic range can be obtained. The buffer amplifiers are provided to permit control of attack time and recovery time independent of each other. Partitioned as shown in the block diagram, the IC allows flexibility in the design of system levels that optimize DC shift, ripple distortion, tracking accuracy and noise floor for a wide range of application requirements.

Gain Cell

Figure 4 shows the circuit configuration of the gain cell. Bases of the differential pairs Q_1 - Q_2 and Q_3 - Q_4 are both tied to the output and inputs of OPA A₁. The negative feedback through Q_1 holds the V_{BE} of Q_1 - Q_2 and the V_{BE} of Q_3 - Q_4 equal. The following relationship can be derived from the transistor model equation in the forward active region.

$$\Delta V_{BE_{Q3Q4}} = \Delta_{BE_{Q1Q2}}$$

$$(V_{BE} = V_T I_{IN} IC/IS)$$

$$V_T I_n \left(\frac{\frac{1}{2}I_G + \frac{1}{2}I_O}{I_S}\right) - V_T I_n \left(\frac{\frac{1}{2}I_G - \frac{1}{2}I_O}{I_S}\right)$$

where $I_{IN} = \frac{V_{IN}}{R_1}$ $R_1 = 6.8k\Omega$

 $I_1 = 140\mu A$ $I_2 = 280\mu A$

$$\begin{split} & \mathsf{V}_{\mathsf{T}}\mathsf{I}_{\mathsf{n}} \, \left(\frac{\mathsf{I}_{\mathsf{1}} + \mathsf{I}_{\mathsf{I}\mathsf{N}}}{\mathsf{I}_{\mathsf{S}}}\right) - \, \mathsf{V}_{\mathsf{T}}\mathsf{I}_{\mathsf{n}} \, \left(\frac{\mathsf{I}_{\mathsf{2}} - \mathsf{I}_{\mathsf{1}} - \mathsf{I}_{\mathsf{I}\mathsf{N}}}{\mathsf{I}_{\mathsf{S}}}\right) \, (2) \\ & \text{where} \, \, \mathsf{I}_{\mathsf{I}\mathsf{N}} \, = \frac{\mathsf{V}_{\mathsf{I}\mathsf{N}}}{\mathsf{R}_{\mathsf{1}}} \\ & \qquad \mathsf{R}_{\mathsf{1}} = 6.8 \mathsf{k}\Omega \end{split}$$

 ${\sf I}_O$ is the differential output current of the gain cell and ${\sf I}_G$ is the gain control current of the gain cell.

If all transistors Q_1 through Q_4 are of the same size, equation (2) can be simplified to:

$$I_{O} = \frac{2}{I_{2}} \cdot I_{IN} \cdot I_{G} - \frac{1}{I_{2}}(I_{2} - 2I_{1}) \cdot I_{G}$$
 (3)

The first term of Equation 3 shows the multiplier relationship of a linearized two quadrant transconductance amplifier. The second term is the gain control feedthrough due to the mismatch of devices. In the design, this has been minimized by large matched devices and careful layout. Offset voltage is caused by the device mismatch and it leads to even harmonic distortion. The offset voltage can be trimmed out by feeding a current source within $\pm 25 \mu A$ into the THD trim pin.

The residual distortion is third harmonic distortion and is caused by gain control ripple. In a compandor system, available control of fast attack and slow recovery improve ripple distortion significantly. At the unity gain level of 100mV, the gain cell gives THD (total harmonic distortion) of 0.17% typ. Output noise with no input signals is only 6µV in the audio spectrum (10Hz-20kHz). The output current I_O must feed the virtual ground input of an operational amplifier with a resistor from output to inverting input. The non-inverting input of the operational amplifier has to be biased at V_{REF} if the output current I_O is DC coupled.



Figure 4. Basic Gain Cell Schematic

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Rectifier

The rectifier is a full-wave design as shown in Figure 5. The input voltage is converted to current through the input resistor R_2 and turns on either Q_5 or Q_6 depending on the signal polarity. Deadband of the voltage to current converter is reduced by the loop gain of the gain block A_2 . If AC coupling is used, the rectifier error comes only from input bias current of gain block A_2 . The input bias current is typically about 70nA. Frequency response of the gain block A_2 also causes second-order error at high frequency. The collector current of Q_6 is mirrored and summed at the collector of Q_5 to form the full wave rectified output current I_R . The rectifier transfer function is

$$I_{R} = \frac{V_{IN} - V_{REF}}{R_2}$$
(4)

If $V_{\mbox{IN}}$ is AC-coupled, then the equation will be reduced to:

$$I_{RAC} = \frac{V_{IN}(AVG)}{R_2}$$

The internal bias scheme limits the maximum output current I_R to be around 300 $\mu A.$ Within a $\pm 1dB$ error band the input range of the rectifier is about 52dB.



Figure 5. Simplified Rectifier Schematic

Buffer Amplifier

In audio systems, it is desirable to have fast attack time and slow recovery time for a tone burst input. The fast attack time reduces transient channel overload but also causes low-frequency ripple distortion. The low-frequency ripple distortion can be improved with the slow recovery time. If different attack times are implemented in corresponding frequency spectrums in a split band audio system, high quality performance can be achieved. The buffer amplifier is designed to make this feature available with minimum external components. Referring to Figure 6, the rectifier output current is mirrored into the input and output of the unipolar buffer amplifier A3 through Q_8 , Q_9 and Q_{10} . Diodes D_{11} and D_{12} improve tracking accuracy and provide common-mode bias for A₃. For a positive-going input signal, the buffer amplifier acts like a voltage-follower. Therefore, the output impedance of A₃ makes the contribution of capacitor CR to attack time insignificant. Neglecting diode impedance, the gain Ga(t) for ΔG can be expressed as follows:

$$Ga(t) = (Ga_{INT} - Ga_{FNL} e^{\frac{-t}{\tau_A}} + Ga_{FNL}$$

Ga_{INT}=Initial Gain

Ga_{FNL}=Final Gain

 $\tau_A=R_A \bullet CA=10k \bullet CA$

where τ_A is the attack time constant and R_A is a 10k internal resistor. Diode D_{15} opens the feedback loop of A_3 for a negative-going signal if the value of capacitor CR is larger than capacitor CA. The recovery time depends only on CR \bullet R_R . If the diode impedance is assumed negligible, the dynamic gain G_R (t) for ΔG is expressed as follows.

$$G_{R}(t) = (G_{RINT} - G_{RFNL} e^{\frac{-t}{\tau_{R}}} + G_{RFNL}$$

 $G_R(t)=(G_R INT-G_R FNL) e + G_R FNL$

where τR is the recovery time constant and R_R is a 10k internal resistor. The gain control current is mirrored to the gain cell through Q_{14} . The low level gain errors due to input bias current of A_2 and A_3 can be trimmed through the tracking trim pin into A_3 with a current source of $\pm 3\mu A$.

SA572



Figure 6. Buffer Amplifier Schematic

Basic Expandor

Figure 7 shows an application of the circuit as a simple expandor. The gain expression of the system is given by

$$\frac{V_{OUT}}{V_{IN}} = \frac{2}{I_1} \cdot \frac{R_3 \cdot V_{IN(AVG)}}{R_2 \cdot R_1}$$
(5)

(I₁=140µA)

Both the resistors R₁ and R₂ are tied to internal summing nodes. R₁ is a 6.8k internal resistor. The maximum input current into the gain cell can be as large as 140µA. This corresponds to a voltage level of 140µA • 6.8k=952mV peak. The input peak current into the rectifier is limited to 300µA by the internal bias system. Note that the value of R₁ can be increased to accommodate higher input level. R₂ and R₃ are external resistors. It is easy to adjust the ratio of R₃/R₂ for desirable system voltage and current levels. A small R₂ results in higher gain control current and smaller static and dynamic tracking

error. However, an impedance buffer A_1 may be necessary if the input is voltage drive with large source impedance.

The gain cell output current feeds the summing node of the external OPA A₂. R₃ and A₂ convert the gain cell output current to the output voltage. In high-performance applications, A₂ has to be low-noise, high-speed and wide band so that the high-performance output of the gain cell will not be degraded. The non-inverting input of A₂ can be biased at the low noise internal reference Pin 6 or 10. Resistor R₄ is used to bias up the output DC level of A₂ for maximum swing. The output DC level of A₂ is given by

$$V_{ODC} = V_{REF} \left(1 + \frac{R_3}{R_4} \right) - V_B \frac{R_3}{R_4} \qquad (6)$$

 V_B can be tied to a regulated power supply for a dual supply system and be grounded for a single supply system. CA sets the attack time constant and CR sets the recovery time constant. *5COL

SA572



Figure 7. Basic Expandor Schematic

Basic Compressor

Figure 8 shows the hook-up of the circuit as a compressor. The IC is put in the feedback loop of the OPA A_1 . The system gain expression is as follows:

$$\frac{V_{OUT}}{V_{IN}} = \left(\frac{I_1}{2} \cdot \frac{R_2 \cdot R_1}{R_3 \cdot V_{IN(AVG)}}\right)^{\frac{1}{2}}$$
(7)

 $R_{DC1},\,R_{DC2},\,and\,CDC$ form a DC feedback for $A_1.$ The output DC level of A_1 is given by

$$V_{ODC} = V_{REF} \left(1 + \frac{R_{DC1} + R_{DC2}}{R_4} \right)$$
(8)
$$- V_{B} \cdot \left(\frac{R_{DC1} + R_{DC2}}{R_4} \right)$$

The zener diodes D_1 and D_2 are used for channel overload protection.



Figure 8. Basic Compressor Schematic

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Basic Compandor System

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The above basic compressor and expandor can be applied to systems such as tape/disc noise reduction, digital audio, bucket brigade delay lines. Additional system design techniques such as bandlimiting, band splitting, pre-emphasis, de-emphasis and equalization are easy to incorporate. The IC is a versatile functional block to achieve a high performance audio system. Figure 9 shows the system level diagram for reference.



Figure 9. SA572 System Level

OUTLINE VERSION

SOT162-1

IEC

075E03

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	A					rom the	origina		scale			1	Q 1.1 1.0	v 0.25	w 0.25	y 0.1

REFERENCES

JEDEC

MS-013AA

SO16: plastic small outline package; 16 leads; body width 7.5 mm

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Product specification

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ISSUE DATE

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UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	с	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES				
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE		
SOT38-4					-92-11-17 95-01-14		

SA572

SOT38-4

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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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